

REPLACEMENT CLAIM

Please substitute the following claims for the pending claims with the same number.

1. (Amended) A packaging process for an image sensing component of which comprising a printed circuit board, a carrier, and a glass plate; wherein said printed circuit board, said carrier, and said glass plate being placed in a main tray, a first tray, and a second tray respectively for said packaging process, comprising the steps of;

performing a rinsing process on said printed circuit board, said carrier, and said glass plate in said main tray, said first tray, and said second tray respectively as a pre-treatment;

dispensing said printed circuit board, and then capturing said carrier in said first tray onto each of said printed circuit board of said main tray;

performing a thermal pressing process and an adhering process on said printed circuit board and said carrier;

dispensing said glass plate, and then collecting said carrier in said first tray to each said printed circuit board of said main tray; and

adhering said glass plate onto said carrier by thermal pressing in the high-pressure working environment.